

Parameter	DTr1 and DTr2
V_{CEO}	50V
I_C	100mA
R_1	10k Ω

●Features

- 1)Two DTC114T chips in a EMT or UMT or SMT package.
- 2)Mounting possible with EMT3 or UMT3 or SMT3 automatic mounting machines.
- 3)Transistor elements are independent, eliminating interference.
- 4)Mounting cost and area can be cut in half.

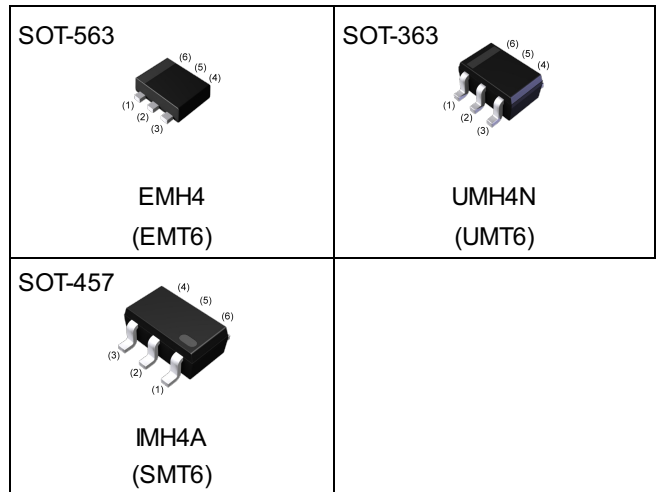
●Application

INVERTER, INTERFACE, DRIVER

●Packaging specifications

Part No.	Package	Package size	Taping code	Reel size (mm)	Tape width (mm)	Basic ordering unit.(pcs)	Marking
EMH4	SOT-563 (EMT6)	1616	T2R	180	8	8000	H4
UMH4N	SOT-363 (UMT6)	2021	TN	180	8	3000	H4
IMH4A	SOT-457 (SMT6)	2928	T110	180	8	3000	H4

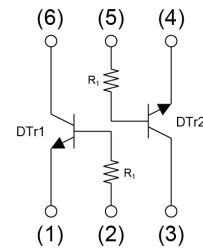
●Outline



●Inner circuit

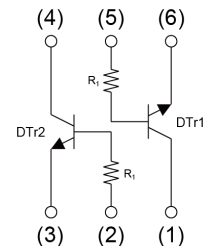
EMH4 / UMH4N

- (1) DTr1 Emitter
- (2) DTr1 Base
- (3) DTr2 Collector
- (4) DTr2 Emitter
- (5) DTr2 Base
- (6) DTr1 Collector



IMH4A

- (1) DTr1 Collector
- (2) DTr2 Base
- (3) DTr2 Emitter
- (4) DTr2 Collector
- (5) DTr1 Base
- (6) DTr1 Emitter



● **Absolute maximum ratings** ($T_a = 25^\circ\text{C}$)

<For DTr1 and DTr2 in common>

Parameter		Symbol	Values	Unit
Collector-base voltage		V_{CBO}	50	V
Collector-emitter voltage		V_{CEO}	50	V
Emitter-base voltage		V_{EBO}	5	V
Collector current		I_{C}	100	mA
Power dissipation	EMH4	P_{D}^{*1*2}	150	mW/Total
	UMH4N	P_{D}^{*1*2}	150	
	IMH4A	P_{D}^{*1*3}	300	
Junction temperature		T_{j}	150	$^\circ\text{C}$
Range of storage temperature		T_{stg}	-55 to +150	$^\circ\text{C}$

● **Electrical characteristics** ($T_a = 25^\circ\text{C}$)

<For DTr1 and DTr2 in common>

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Collector-base breakdown voltage	BV_{CBO}	$I_{\text{C}} = 50\mu\text{A}$	50	-	-	V
Collector-emitter breakdown voltage	BV_{CEO}	$I_{\text{C}} = 1\text{mA}$	50	-	-	V
Emitter-base breakdown voltage	BV_{EBO}	$I_{\text{E}} = 50\mu\text{A}$	5	-	-	V
Collector cut-off current	I_{CBO}	$V_{\text{CB}} = 50\text{V}$	-	-	500	nA
Emitter cut-off current	I_{EBO}	$V_{\text{EB}} = 4\text{V}$	-	-	500	nA
Collector-emitter saturation voltage	$V_{\text{CE(sat)}}$	$I_{\text{C}} = 10\text{mA}, I_{\text{B}} = 1\text{mA}$	-	-	300	mV
DC current gain	h_{FE}	$V_{\text{CE}} = 5\text{V}, I_{\text{C}} = 1\text{mA}$	100	250	600	-
Input resistance	R_1	-	7	10	13	k Ω
Transition frequency	f_{T}^{*4}	$V_{\text{CE}} = 10\text{V}, I_{\text{E}} = -5\text{mA}, f = 100\text{MHz}$	-	250	-	MHz

*1 Each terminal mounted on a reference land.

*2 120mW per element must not be exceeded.

*3 200mW per element must not be exceeded.

*4 Characteristics of built-in transistor.

● **Electrical characteristic curves** ($T_a = 25^\circ\text{C}$)
 <For DTr1 and DTr2 in common>

Fig.1 Grounded Emitter Propagation Characteristics

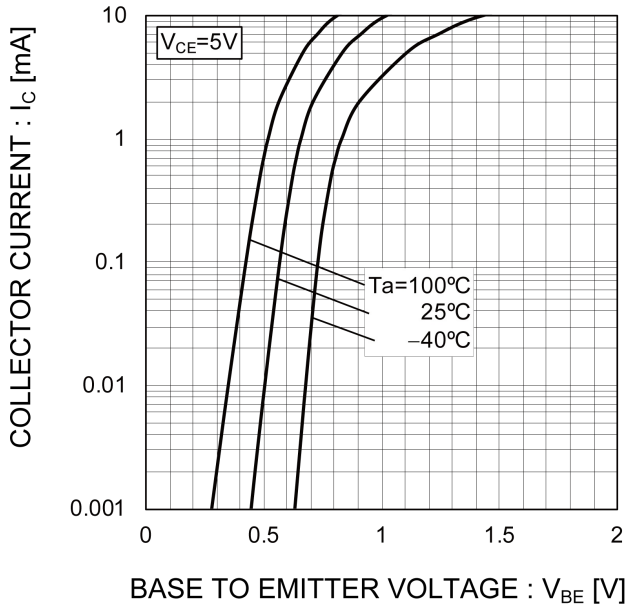


Fig.2 Grounded Emitter Output Characteristics

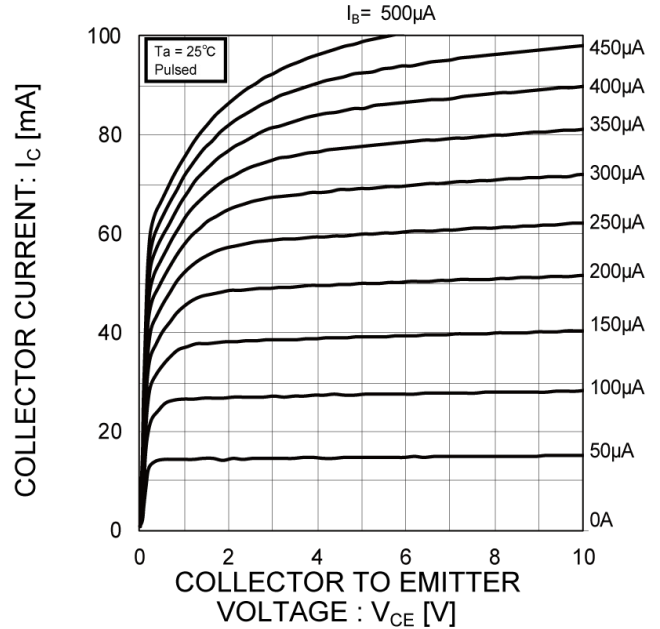


Fig.3 DC Current Gain vs. Collector Current

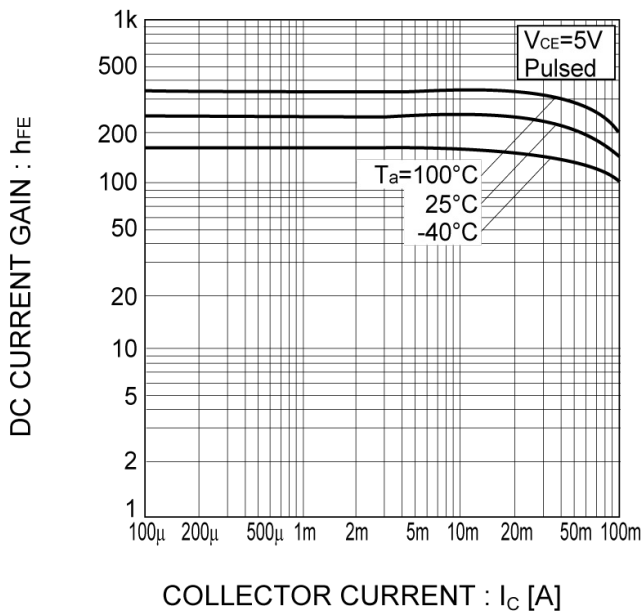
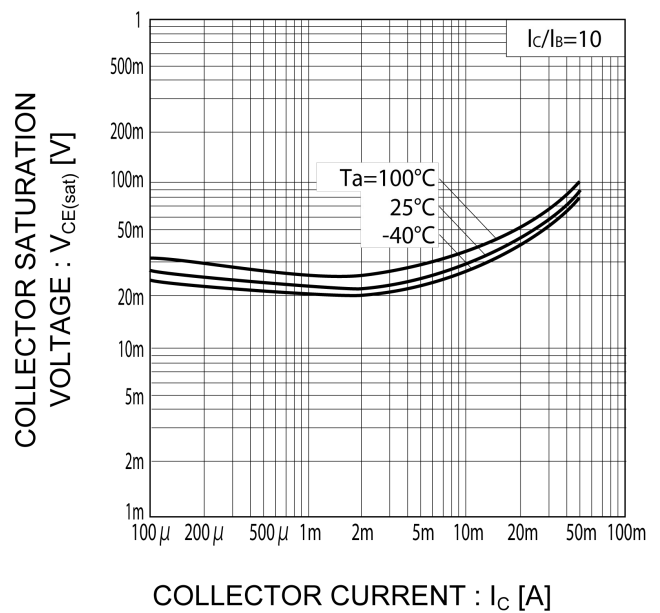
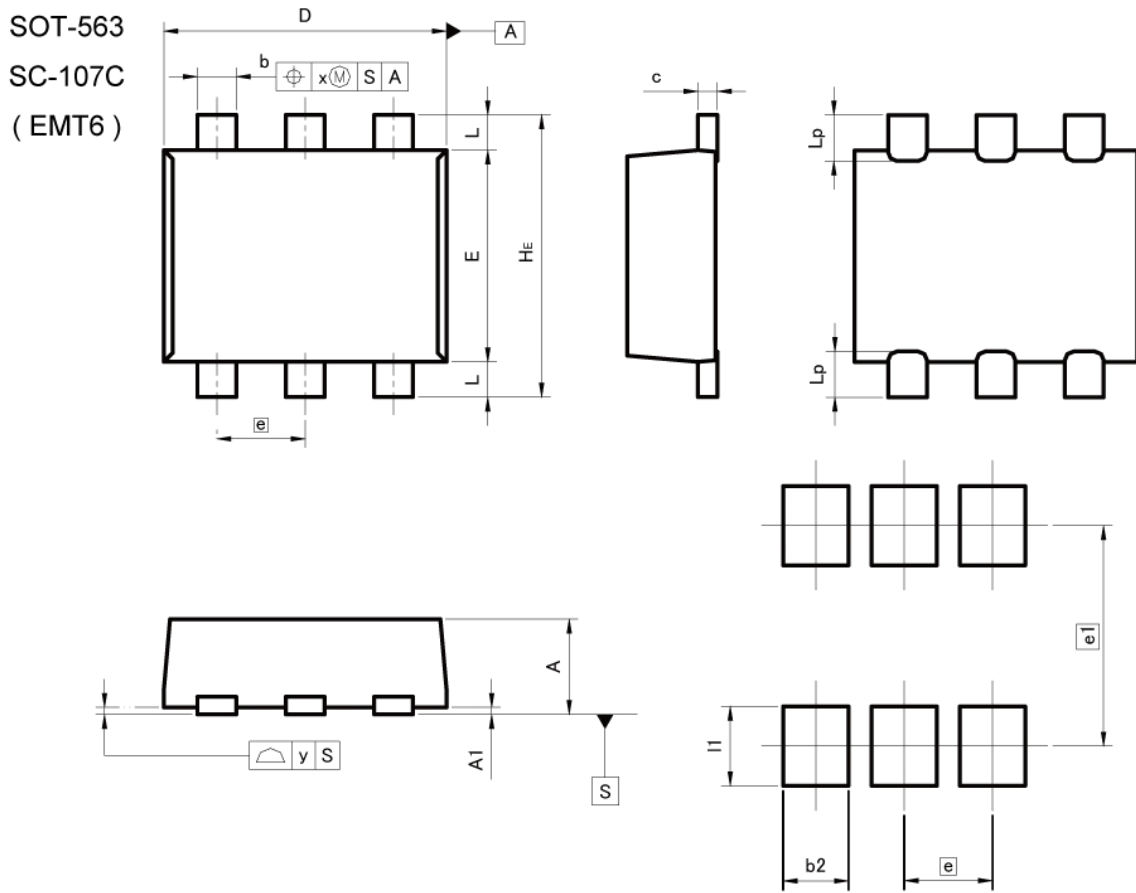


Fig.4 Collector-Emitter Saturation Voltage vs. Collector Current



●Dimensions



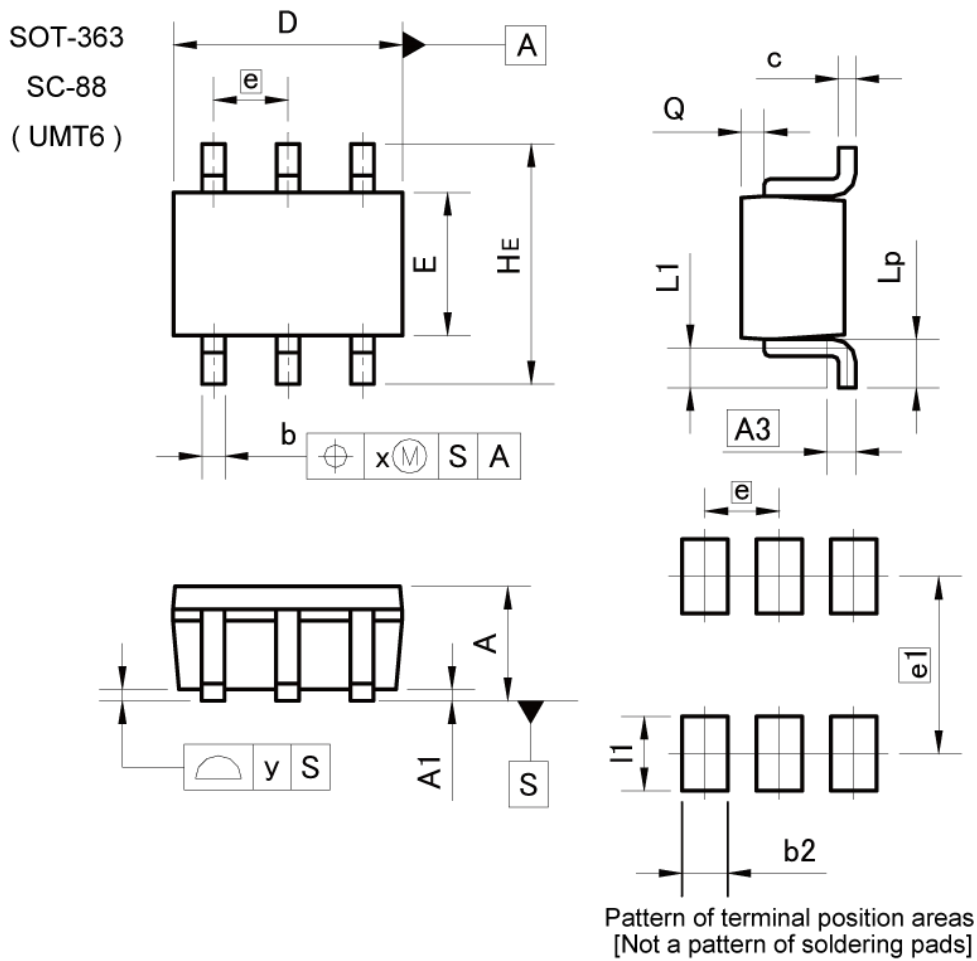
Pattern of terminal position areas
[Not a pattern of soldering pads]

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.45	0.55	0.018	0.022
A1	0.00	0.10	0.000	0.004
b	0.17	0.27	0.007	0.011
c	0.08	0.18	0.003	0.007
D	1.50	1.70	0.059	0.067
E	1.10	1.30	0.043	0.051
e	0.50		0.020	
HE	1.50	1.70	0.059	0.067
L	0.10	0.30	0.004	0.012
Lp	-	0.35	-	0.014
x	-	0.10	-	0.004
y	-	0.10	-	0.004

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b2	-	0.37	-	0.015
e1	1.25		0.049	
I1	-	0.45	-	0.018

Dimension in mm/inches

●Dimensions



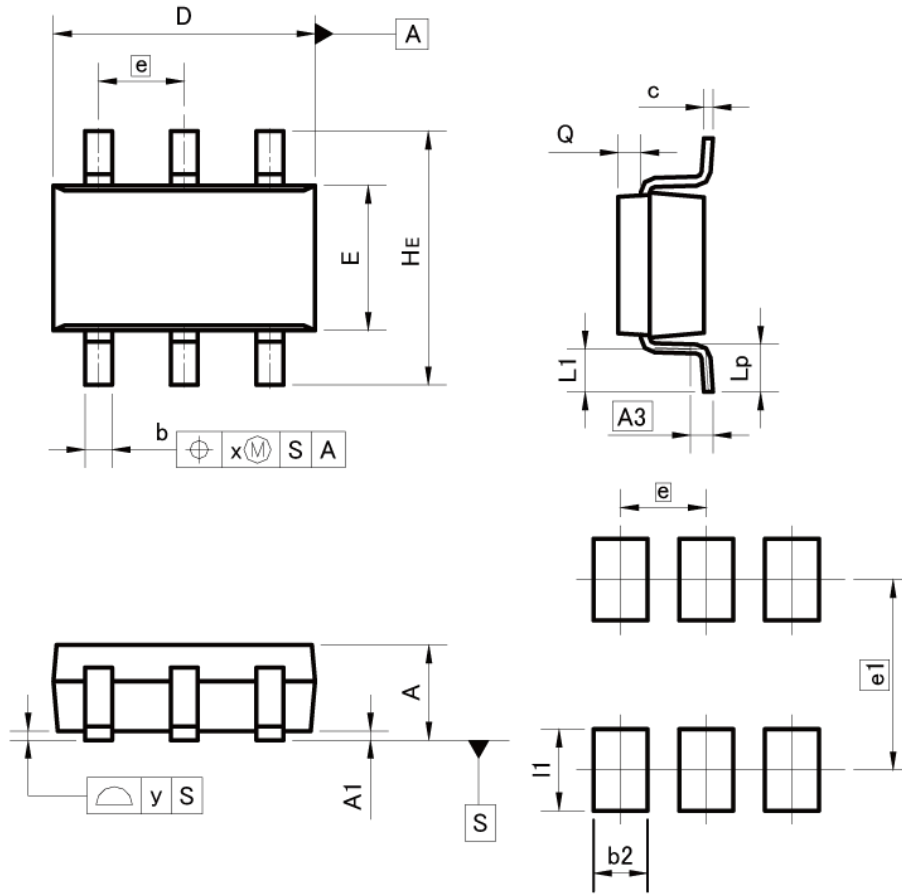
DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.80	1.00	0.031	0.039
A1	0.00	0.10	0.000	0.004
A3	0.25		0.010	
b	0.15	0.30	0.006	0.012
c	0.10	0.20	0.004	0.008
D	1.90	2.10	0.075	0.083
E	1.15	1.35	0.045	0.053
e	0.65		0.026	
HE	2.00	2.20	0.079	0.087
L1	0.20	0.50	0.008	0.020
Lp	0.25	0.55	0.010	0.022
Q	0.10	0.30	0.004	0.012
x	-	0.10	-	0.004
y	-	0.10	-	0.004

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b2	-	0.40	-	0.016
e1	1.55		0.061	
I1	-	0.65	-	0.026

Dimension in mm/inches

●Dimensions

SOT-457
 SC-74
 (SMT6)



Pattern of terminal position areas
 [Not a pattern of soldering pads]

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.00	1.30	0.039	0.051
A1	0.00	0.10	0.000	0.004
A3	0.25		0.010	
b	0.25	0.40	0.010	0.016
c	0.09	0.25	0.004	0.010
D	2.80	3.00	0.110	0.118
E	1.50	1.80	0.059	0.071
e	0.95		0.037	
HE	2.60	3.00	0.102	0.118
L1	0.30	0.60	0.012	0.024
Lp	0.40	0.70	0.016	0.028
Q	0.20	0.30	0.008	0.012
x	-	0.20	-	0.008
y	-	0.10	-	0.004

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b2	-	0.60	-	0.024
e1	2.10		0.083	
I1	-	0.90	-	0.035

Dimension in mm/inches

Notice

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JAPAN	USA	EU	CHINA
CLASS III	CLASS III	CLASS II b	CLASS III
CLASS IV		CLASS III	

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 - Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - Sealing or coating our Products with resin or other coating materials
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 - Use of the Products in places subject to dew condensation
- The Products are not subject to radiation-proof design.
- Please verify and confirm characteristics of the final or mounted products in using the Products.
- In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of Ionizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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